

**Amendments to the Specification**

On page 1, lines 1-5, please delete the "Cross Reference To Related Applications" added by the Preliminary Amendment dated April 7, 1997, and substitute the following.

**--Cross Reference To Related Applications**

This application is a continuation of Serial No. 08/541,291, filed on 10/10/1995 (abandoned), which is a continuation of Serial No. 08/120,628, filed on 09/13/1993 (abandoned), which is a continuation of Serial No. 08/073,003, filed on 06/07/1993 (abandoned), which is a continuation-in-part of Serial No. 07/709,858, filed on 06/04/1991 (abandoned), and a continuation-in-part of Serial No. 07/788,065, filed on 11/05/1991, Patent No. 5,440,240, and a continuation-in-part of Serial No. 07/981,956, filed on 11/24/1992, Patent No. 5,539,324.

This application is related to Serial No. 08/406,637, filed on 03/20/1995, Patent No. 5,585,282. --

In the paragraph on page 17, lines 1-18 please make the following changes.

-- The die 21 is placed on the intermediate substrate 41 with bondpads 27 on the die 21 aligned with the die contacts 43. Raised asperities 69 are located at the point of contact of the die contacts 43 with the bondpads 37. The raised asperities 69 are formed on the die contacts 43. In the case of a ceramic intermediate substrate 41, the raised asperities 69 are formed by a combination of photoplatting techniques and doinking. Other techniques for depositing material may be used in lieu of photoplatting, such as stenciling, screen printing or direct writing. The doinking process is described in copending U.S. Patent Application serial no. 07/898,617, filed on 06/15/1992, for PROCESS FOR FORMING RAISED SURFACE IRREGULARITIES BY ULTRASONIC FORGING, by Alan Wood, David Hembree, and Warren Farnworth, and U.S. Patent Application Serial No. 07/898,625, filed on 06/15/1992, now U.S. Patent No. 5,249,450, [          ] (~~s.n. 7/898,625~~)<sup>1</sup> for PROBEHEAD FOR ULTRASONIC FORGING, by Alan Wood, David Hembree, Larry Cromar and Warren Farnworth. It is anticipated that the intermediate substrate 41 may be repeatedly used, and the die contacts 43 re-doinked between uses.--